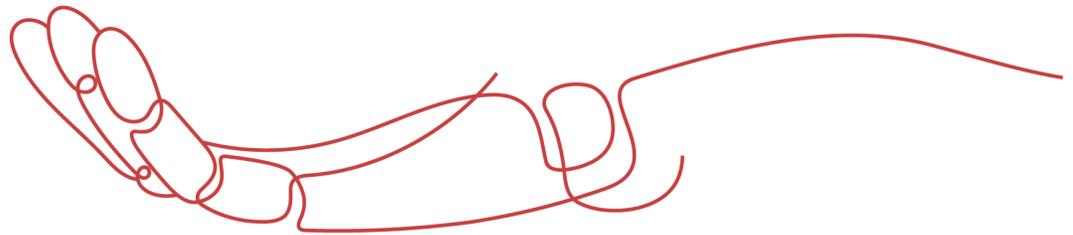


PRODUCT DATA SHEET



To learn more about JGSEMI, please visit our website at



Datasheet



Resources

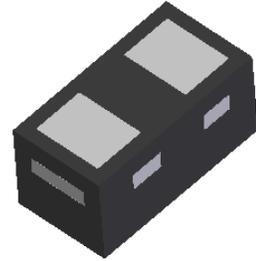


Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

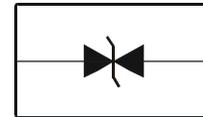
Features

- Ultra-Small, Low Profile Leadless Surface Mount Package (0.6 x 0.3 x 0.3mm)
- Provides ESD Protection per IEC 61000-4-2 Standard:
Air – $\pm 30\text{kV}$, Contact – $\pm 25\text{kV}$
- 1 Channel of ESD Protection
- Low Channel Input Capacitance
- Typically Used in Cellular Handsets, Portable Electronics, Communication Systems, Computers and Peripherals


DFN0603

Mechanical Data

- Case Material: Molded Plastic, “Green” Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish –Matte Tin over Copper Leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.0002 grams (Approximate)


Device Schematic

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

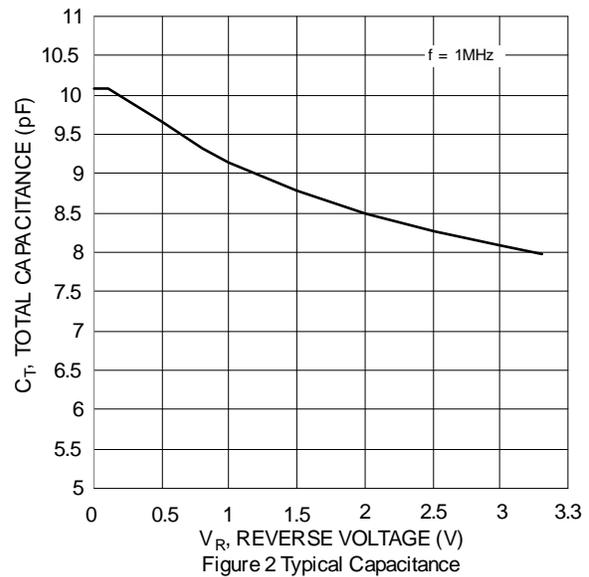
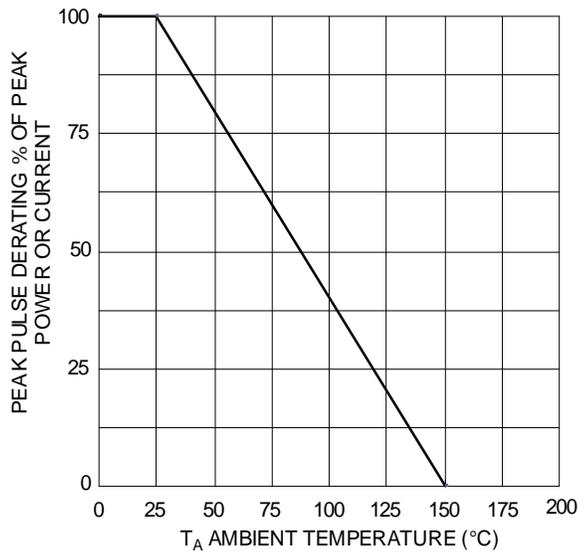
Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	P_{PP}	35	W	8/20 μs , Per Fig. 3
Peak Pulse Current	I_{PP}	5	A	8/20 μs , Per Fig. 3
ESD Protection – Contact Discharge	$V_{ESD_Contact}$	± 25	kV	IEC 61000-4-2 Standard
ESD Protection – Air Discharge	V_{ESD_Air}	± 30	kV	IEC 61000-4-2 Standard

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P_D	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	500	$^{\circ}C/W$
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	$^{\circ}C$

Electrical Characteristics (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Standoff Voltage	V_{RWM}	—	—	3.3	V	—
Channel Leakage Current (Note 6)	I_{RM}	—	10	100	nA	$V_{RWM} = 3.3V$
Clamping Voltage, Positive Transients	V_{CL}	—	4.5 5.8	5.4 7.0	V	$I_{PP} = 1A, t_P = 8/20\mu s$ $I_{PP} = 5A, t_P = 8/20\mu s$
Breakdown Voltage	V_{BR}	3.8	—	6.5	V	$I_R = 1mA$
Differential Resistance	R_{DIF}	—	0.3	—	Ω	$I_R = 1A$
Channel Input Capacitance	C_T	—	10	13	pF	$V_R = 0V, f = 1MHz$



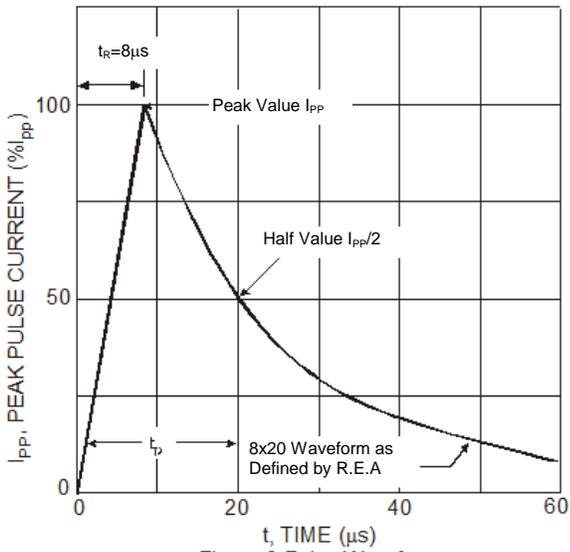


Figure 3 Pulse Waveform

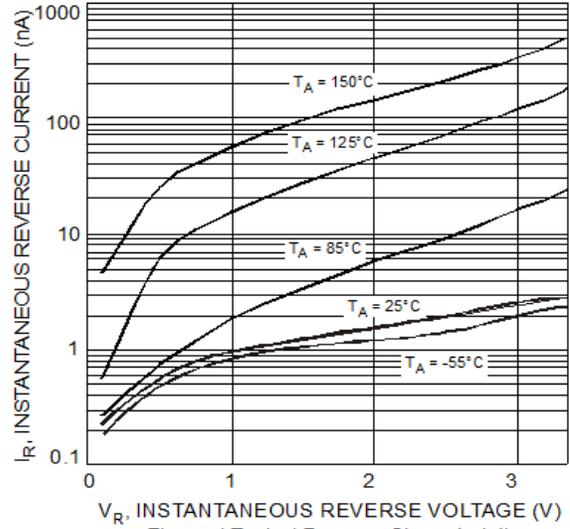


Figure 4 Typical Reverse Characteristics

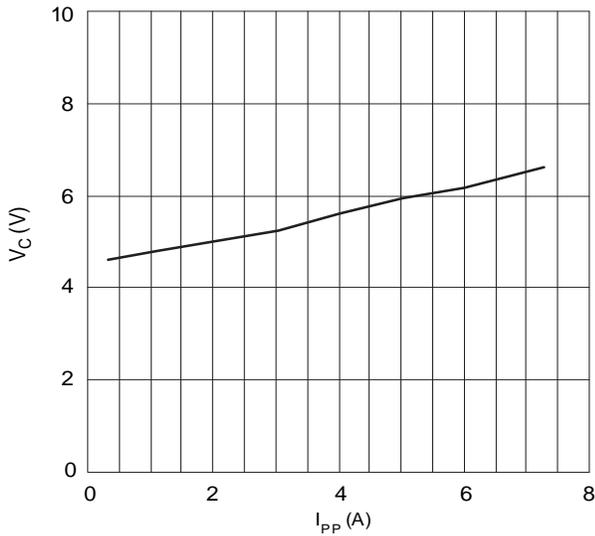


Figure 5 Typical Peak Clamping Voltage V_C vs. Peak Pulse Current I_{PP}

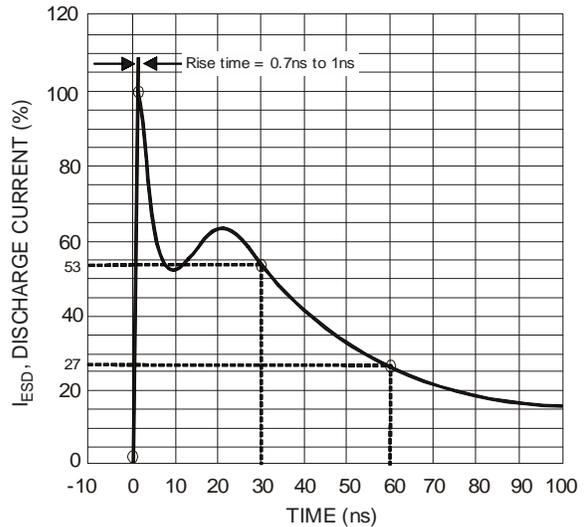


Figure 6 ESD Discharge Current Wave Form IEC 6100-4-2 (330 Ω /150pF)

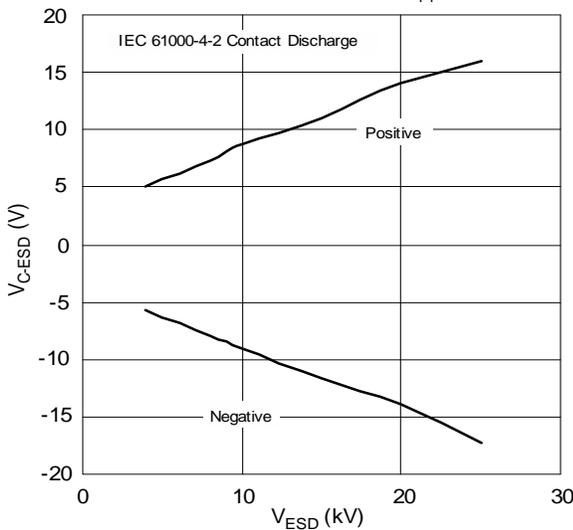


Figure 7 Typical Clamping Voltage vs. Contact Discharge Voltage

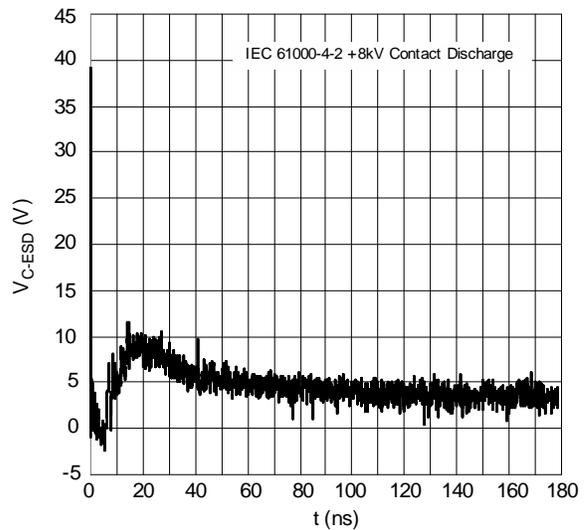
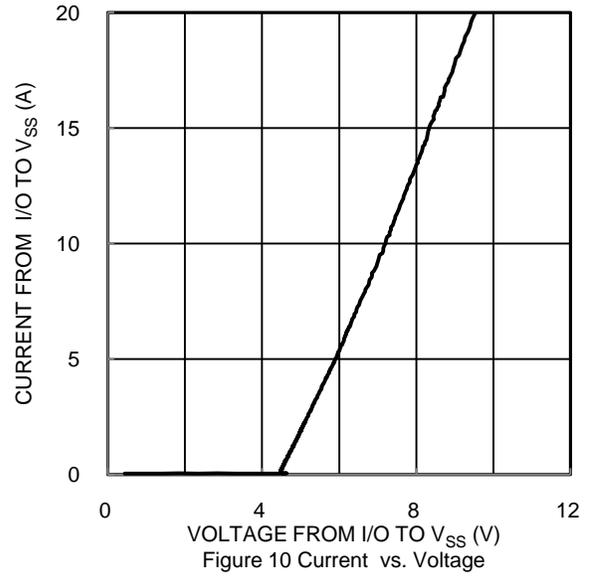
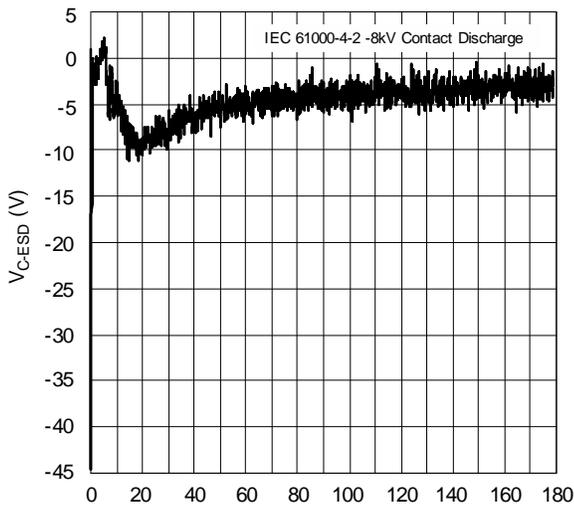
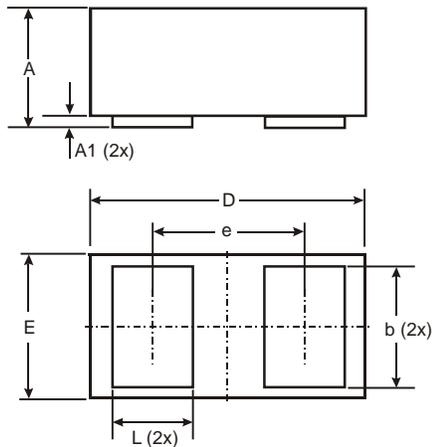


Figure 8 Typical Clamping Performance @ 8kV Contact Discharge



Package Outline Dimensions



X3-DFN0603-2			
Dim	Min	Max	Typ
A	0.27	0.35	0.30
A1	0.00	0.03	0.02
b	0.19	0.29	0.24
D	0.595	0.645	0.62
E	0.295	0.345	0.32
e	-	-	0.355
L	0.14	0.24	0.19
All Dimensions in mm			

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